

APPENDIX
(Showing How Claim 88, 89, 90, and 101 Have Been Amended)

88. (Amended) An integrated circuit structure comprising:

[multiple] a plurality of substrates having integrated circuits formed thereon; and

between adjacent substrates, a non-polymeric bonding layer bonding together the adjacent substrates, the bonding layer being formed by bonding first and second substantially planar surfaces having a bond-forming material throughout a majority of the surface area thereof.

89. (Amended) The apparatus of claim 88, further comprising vertical interconnects having vertical interconnect segments formed of a first metal [pad] contact on a first substrate bonded to a second aligned metal [pad] contact on a second adjacent substrate.

90. (Amended) The apparatus of claim 89, wherein [multiple] the plurality of aligned vertical interconnect segments are joined to form a vertical interconnect between non-adjacent substrates.

101. (Amended) A stacked integrated circuit comprising:

[multiple] a plurality of integrated circuit substrates having formed on corresponding surfaces thereof complementary patterns of a material bondable using thermal diffusion bonding; and

a thermal diffusion bonded region between the complementary patterns.